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Applicant: §
Arjun Selvakumar et al. §
US Application No.: §
International Application No: §
PCT/US00/06832 §
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Title: **Low Stress Die Attachment** §

EB
SA
JK
3/1/02

PRELIMINARY AMENDMENT

With the transmission of the filing of the referenced application under 35 USC 3.71, Applicants submit the following Preliminary Amendment.

IN THE CLAIMS

Please delete the originally filed claims 1-2.

Please add the following new claims and proceed with the national examination procedures under 35 USC 3.71:

- 1 1. An apparatus including thermal stress reduction, comprising:
 a package;
 a mass ¹⁰⁴ coupled to the package, the mass having a surface, the mass further including an active region; and ¹⁰⁸
 one or more substantially rigid members for attaching at least one point on the surface to the package to create a resilient coupling between the mass and the package, wherein at least a portion of the active region is spaced apart from the at least one point of attachment.